

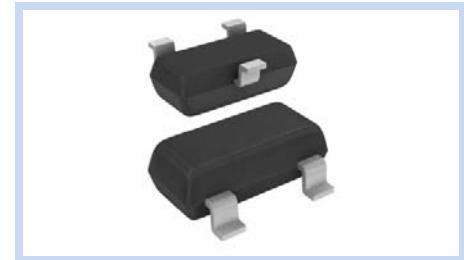
**N-Channel MOSFET  
20V 0.7A 300mW SOT-523 ESD**

MFT2NA70S523E

**MERITEK**

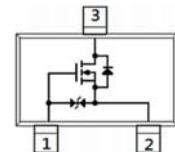
## FEATURE

- $R_{DS(ON)} < 150\text{m}\Omega$ ,  $V_{GS} = 4.5\text{V}$ ,  $I_D = 0.7\text{A}$
- $R_{DS(ON)} < 220\text{m}\Omega$ ,  $V_{GS} = 2.5\text{V}$ ,  $I_D = 0.5\text{A}$
- $R_{DS(ON)} < 400\text{m}\Omega$ ,  $V_{GS} = 1.8\text{V}$ ,  $I_D = 0.2\text{A}$
- **ESD Protected**
- **Low Voltage Drive**
- **Advanced Trench Process Technology**
- **Specially Designed for Switch Load, PWM Application,etc**



## MECHANICAL DATA

- Case: SOT-523 Package
- Terminals: Solderable per MIL-STD-750, Method 2026

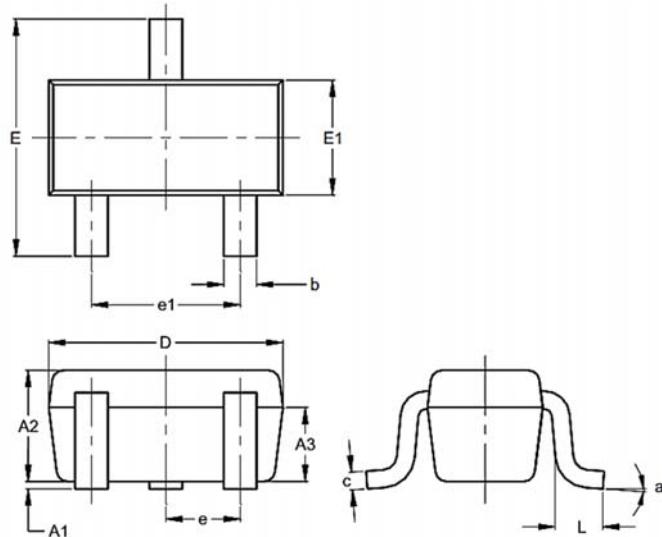


## MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	
Continuous Drain Current	$I_D$	0.7	A
Pulsed Drain Current	$I_{DM}$	2.8	
Power Dissipation	$P_D$	300	W
		2.4	$\text{mW}/^\circ\text{C}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	- 55 to + 150	$^\circ\text{C}$
Typical Thermal Junction to Ambient	$R_{eJA}$	417	$^\circ\text{C}/\text{W}$

## DIMENSIONS

Item	Min (mm)	Max (mm)
A1	-	0.10
A2	0.60	0.80
A3	0.45	0.65
b	0.15	0.30
C	0.10	0.20
D	1.50	1.70
E	1.45	1.75
E1	0.75	0.85
e	0.50 BSC	
e1	0.90	1.10
L	0.20	0.40
a	0°	8°



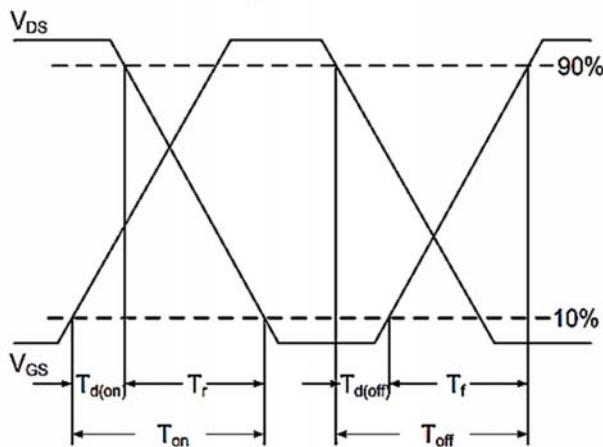
## ELECTRICAL CHARACTERISTICS

Off Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	$BV_{DS(B)}$	20	-	-	V
Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=20V$	$I_{DS(0)}$	-	0.01	1	$\mu A$
Gate-Body Leakage Current	$V_{GS}=\pm 8V, V_{DS}=0V$	$I_{GSS}$	-	$\pm 2$	$\pm 10$	
On Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	$V_{GS(th)}$	0.5	0.78	1.0	
Static Drain Source On-Resistance	$V_{GS}=4.5V, I_D=700mA$	$R_{DS(on)}$	-	129	150	$m\Omega$
	$V_{GS}=2.5V, I_D=500mA$		-	167	220	
	$V_{GS}=1.8V, I_D=200mA$		-	260	400	
Dynamic Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Total Gate Charge	$V_{GS}=4.5V, V_{DS}=10V, I_D=0.7A$	$Q_g$	-	1.6	-	$nC$
Gate-Source Charge		$Q_{gs}$	-	0.3	-	
Gate-Drain Charge		$Q_{gd}$	-	0.4	-	
Input Capacitance	$V_{GS}=0V, V_{DS}=10V, f=1MHz$	$C_{iss}$	-	92	-	$pF$
Output Capacitance		$C_{oss}$	-	25	-	
Reverse Transfer Capacitance		$C_{rss}$	-	9	-	
Turn-On Delay Time	$V_{GS}=4.5V, V_{DD}=10V, I_D=0.7A, R_G=6\Omega$	$t_{d(on)}$	-	6	-	$ns$
Rise Time		$t_r$	-	26	-	
Turn-Off Delay Time		$t_{d(off)}$	-	41	-	
Fall Time		$t_f$	-	31	-	
Drain-Source Body Diode	Conditions	Symbol	Min	Typ.	Max	Unit
Drain-Source Foward Current	-	$I_s$	-	-	0.4	mA
Diode Forward Voltage	$V_{GS}=0V, I_s=1A$	$V_{SD}$	-	0.89	1.2	V

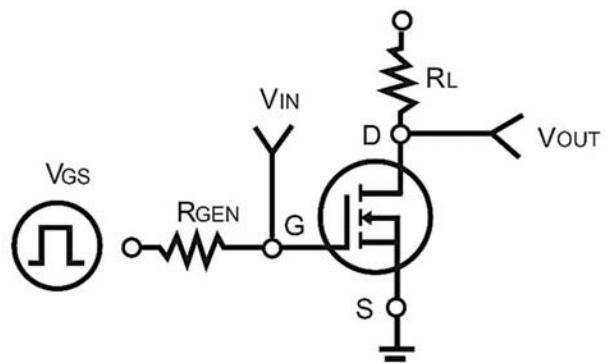
Note:

1. Pulse width  $\leq 300\mu s$ , Duty cycle  $\leq 2\%$
2. Essentially independent of operating temperature
3.  $R_{JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins mounted on 1 inch FR-4 with 2oz. Square pad of copper
4. The maximum current rating is package limited

Switching Time Waveform



Switching Test Circuit



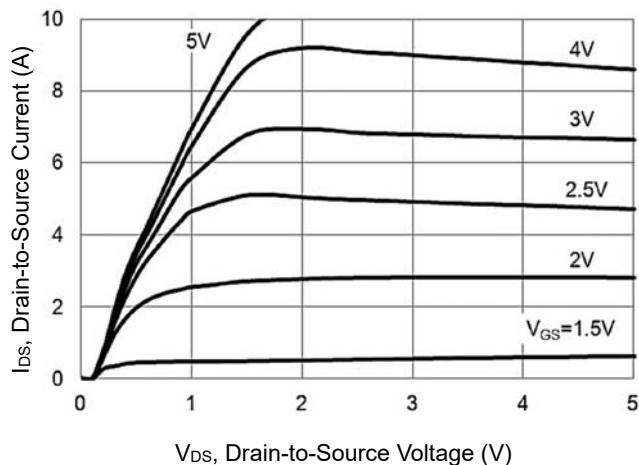
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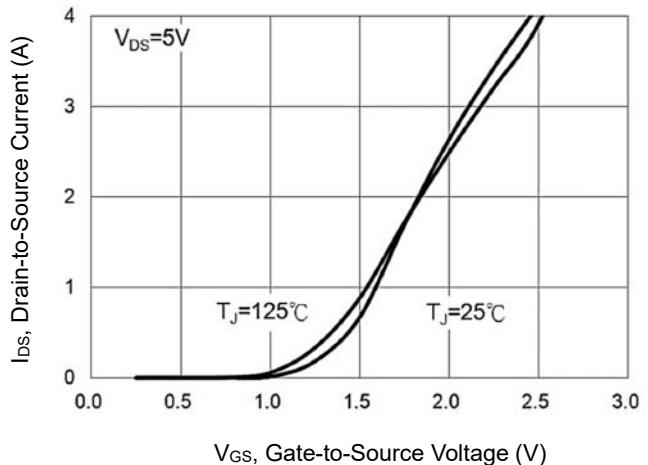
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**CHARACTERISTIC CURVES**

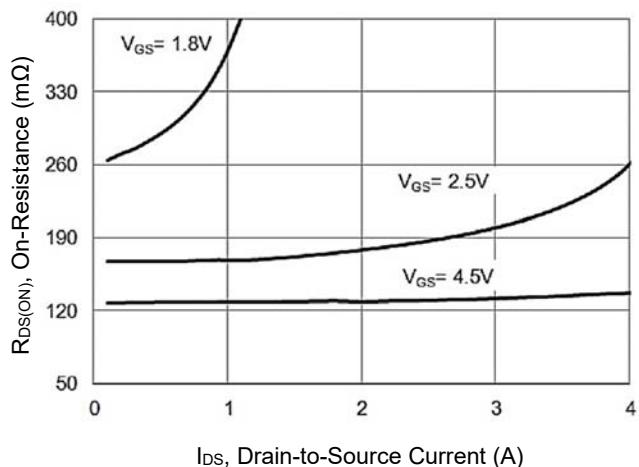
**On-Region Characteristics**



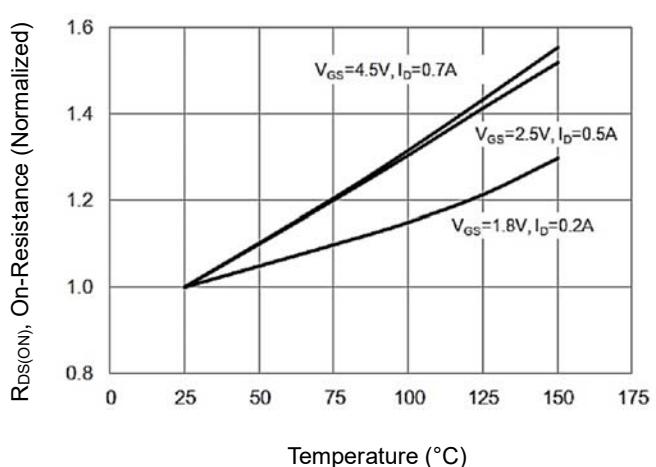
**Transfer Characteristics**



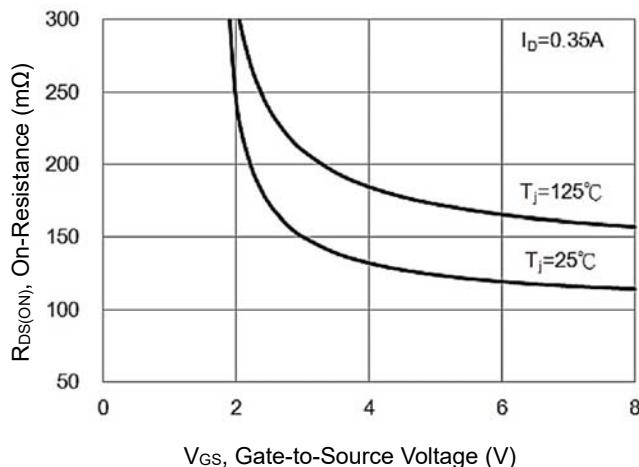
**On-Resistance vs Drain Current**



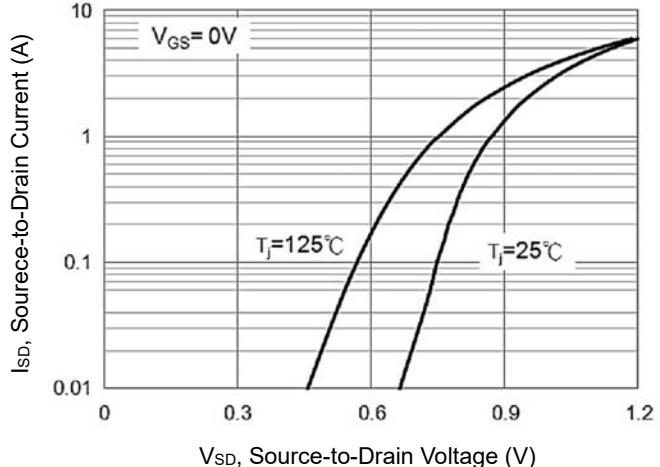
**On-Resistance vs Junction Temperature**



**On-Resistance Variation with  $V_{GS}$**



**Body Diode Characteristics**



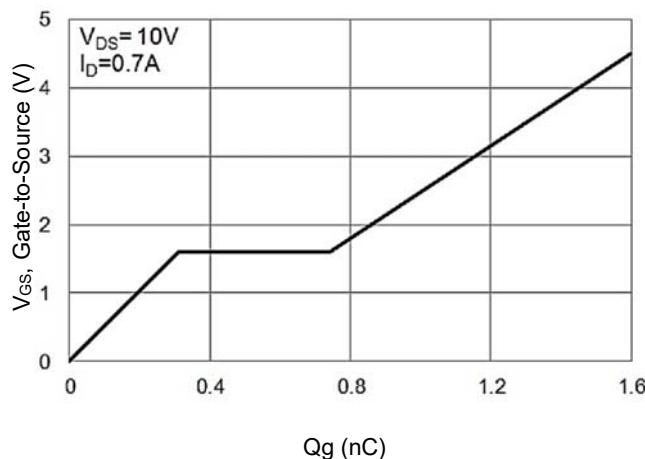
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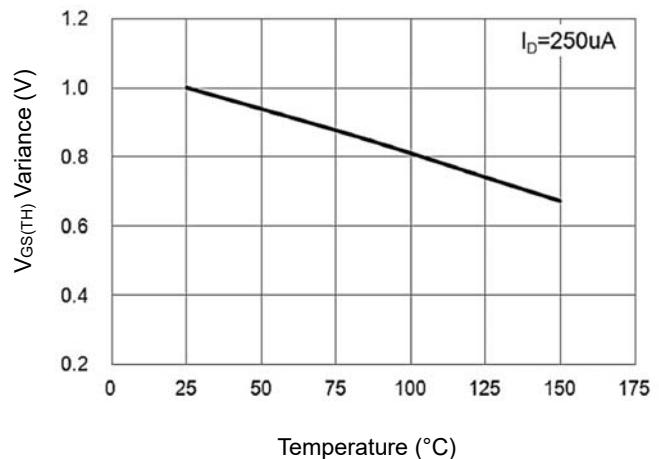
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## CHARACTERISTIC CURVES

Gate-Charge Characteristics



Threshold Voltage Variation with Temperature



Capacitance vs Drain-Source Voltage

